



Braga, 6-10<sup>th</sup> September

STRUCTURAL MODIFICATION OF MgO/CoFeB USING A LOW ENERGY ION BEAM FROM AN ASSISTED DEPOSITION SOURCE

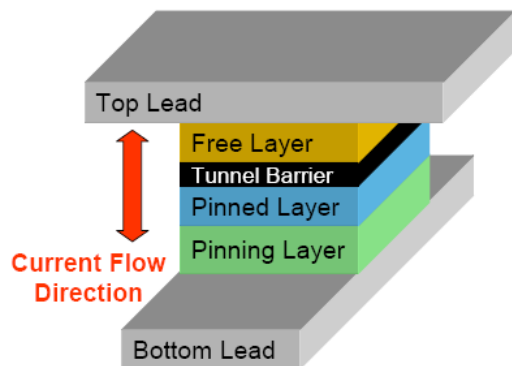
Ricardo Ferreira, Susana Cardoso and Paulo P. Freitas



- I. Motivation
- II. Ion Beam Assisted Deposition
- III. X-ray Diffraction Data of MgO and CoFeB/MgO/CoFeB
- IV. HR-TEM of CoFeB/MgO multilayers
- V. Conclusions

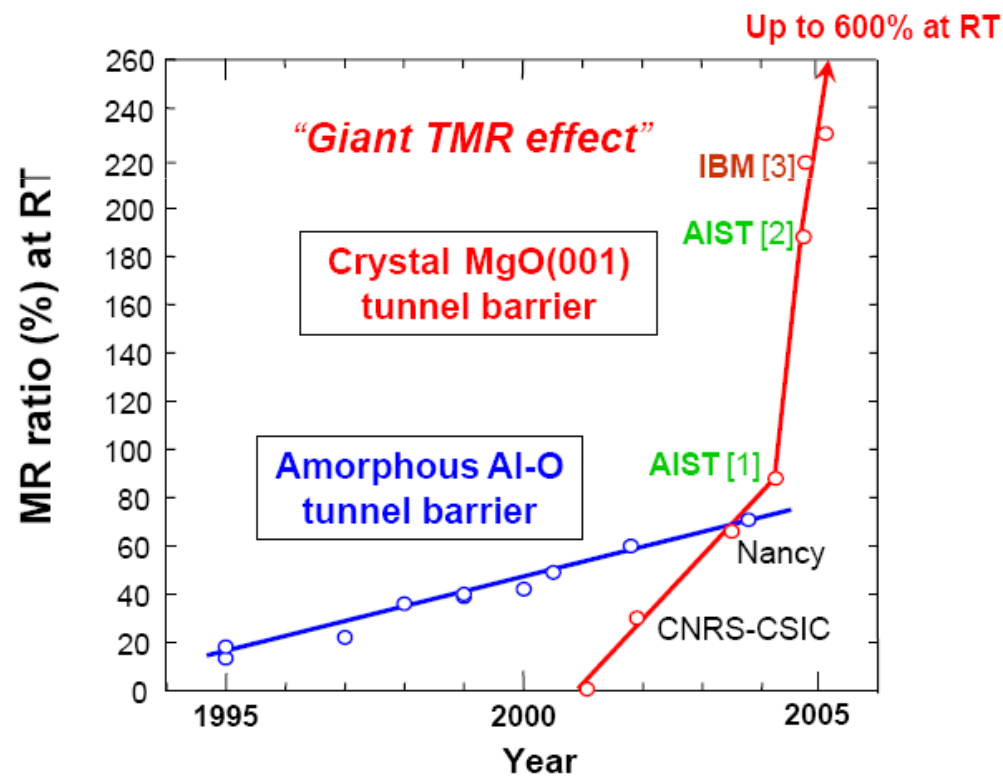
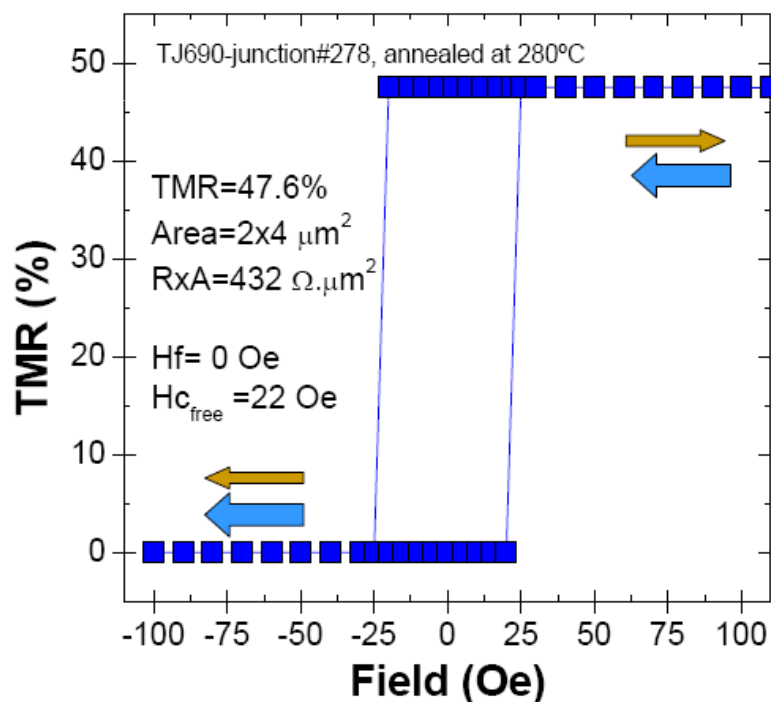
# Motivation

## Magnetic Tunnel Junctions



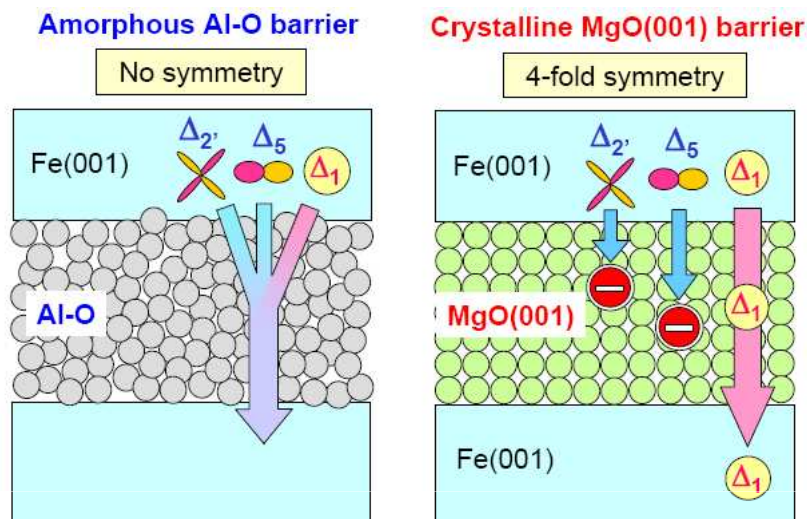
**AlOx MTJs : Magnetic Field Sensors, HDD read heads**

**MgO MTJs : non-volatile memories (MRAM), Spin Transfer Nano-Oscillators (Wi-Fi, novel CMOS magnetic hybrid devices)**



# Motivation

## PVD Deposited MgO Magnetic Tunnel Junctions



As deposited

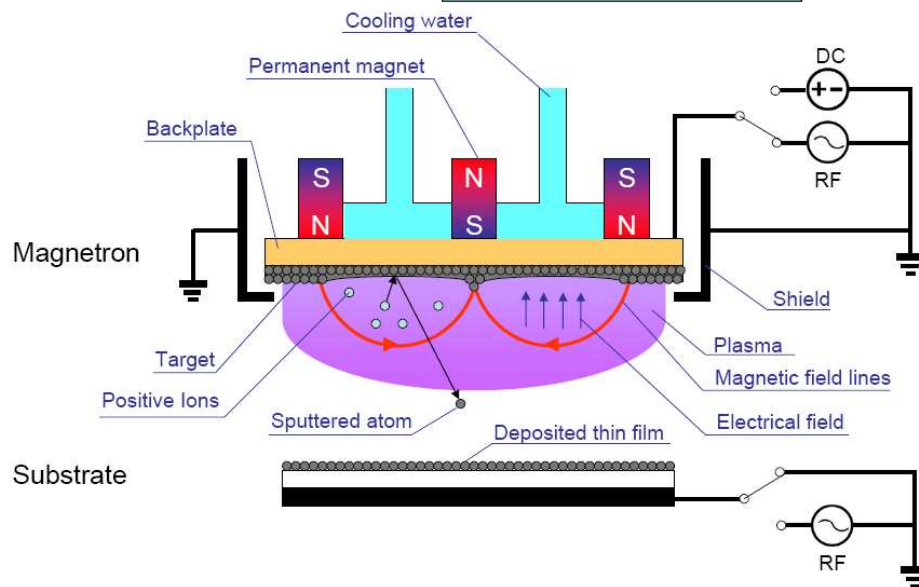
amorphous CoFeB
[100] MgO
amorphous CoFeB

~ 10% TMR

After annealing

bcc [100] CoFeB
[100] MgO
bcc [100] CoFeB

~300% TMR

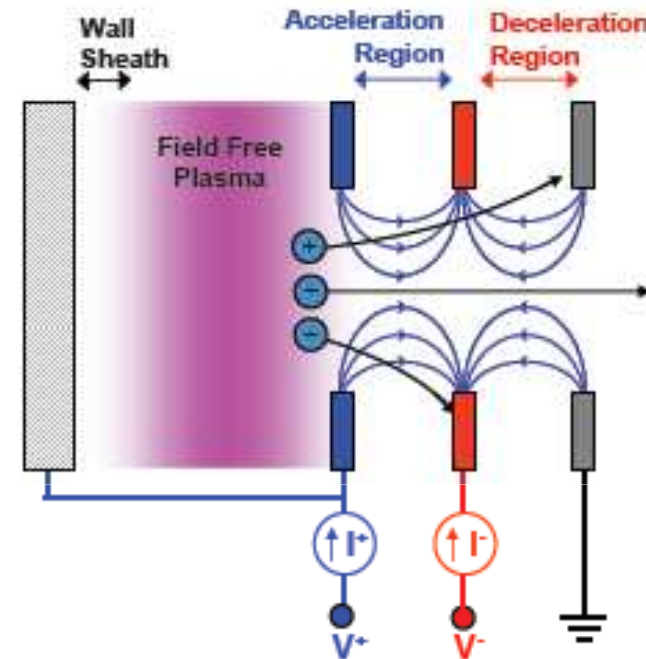
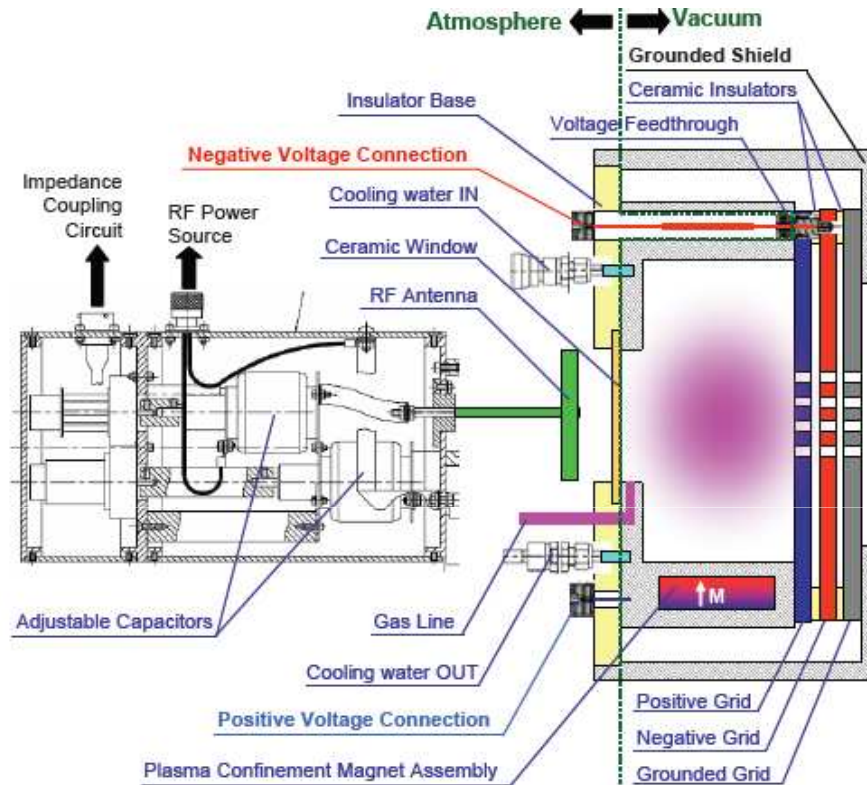


### PVD systems :

- coherently tunneling is routinely achieved
- TMR is strongly system dependent
- best TMR values are still far away from theoretical predictions (>1000%).
- Small number of parameters available (pressure, RF power, distance to substrate)

# Ion Beam Deposition

## Kauffmann type Ion Beam Guns



$V^+$  : Ion Kinetic Energy  
 $I^+$  : Ion Beam Current

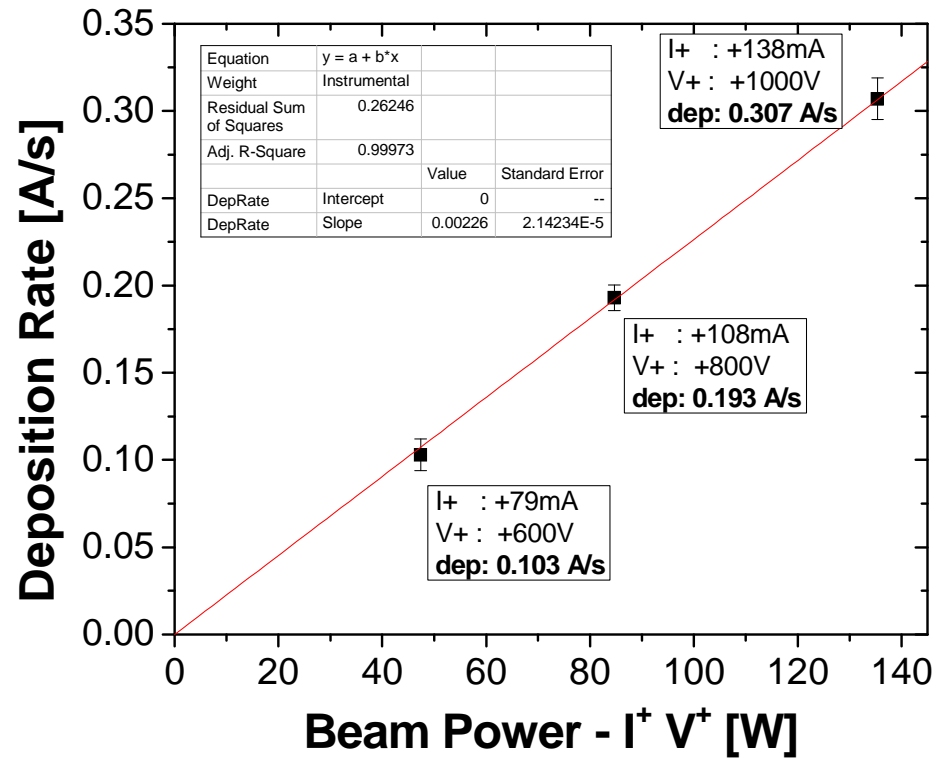
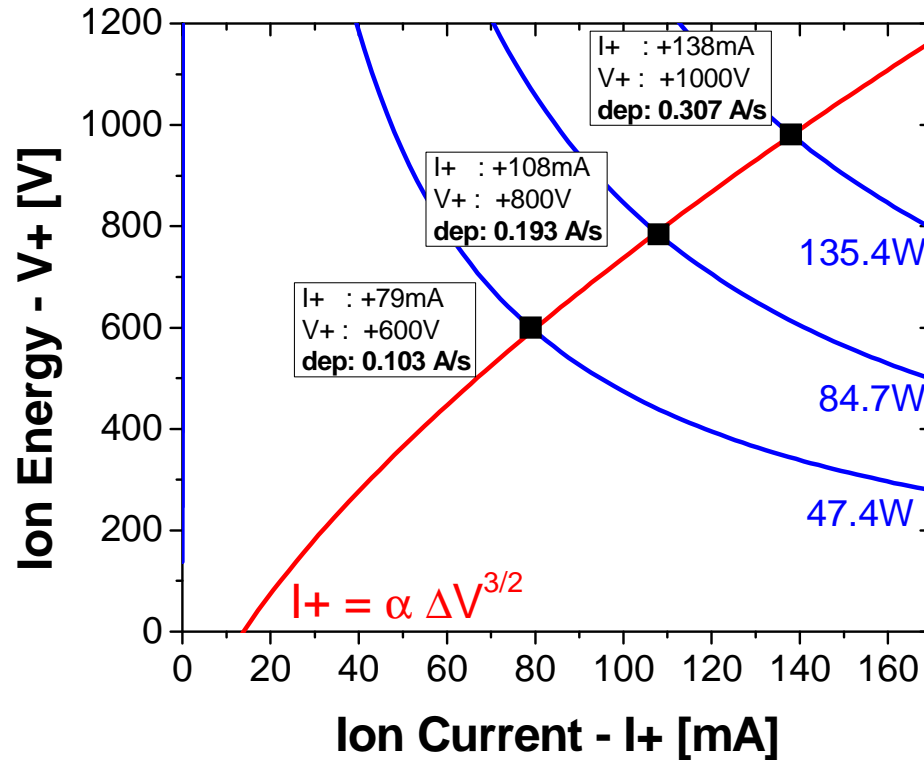
$V^-$  : Extraction Voltage  
 $I^-$  : Ion Beam Divergence

Constant Beam Profile :  $I^+ = \alpha (V^+ - V^-)^{3/2}$

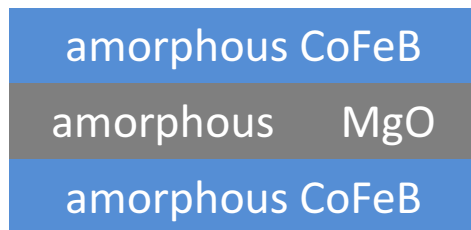
Number of Ions extracted per unit of time and the energy per ion are independent parameters!

# Ion Beam Deposition

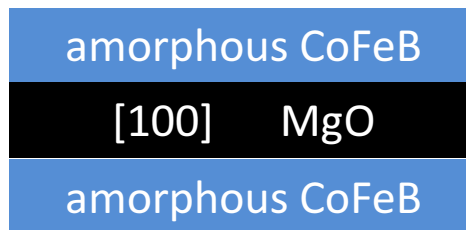
MgO Ion Beam Deposition – Not Assisted



As deposited



After annealing

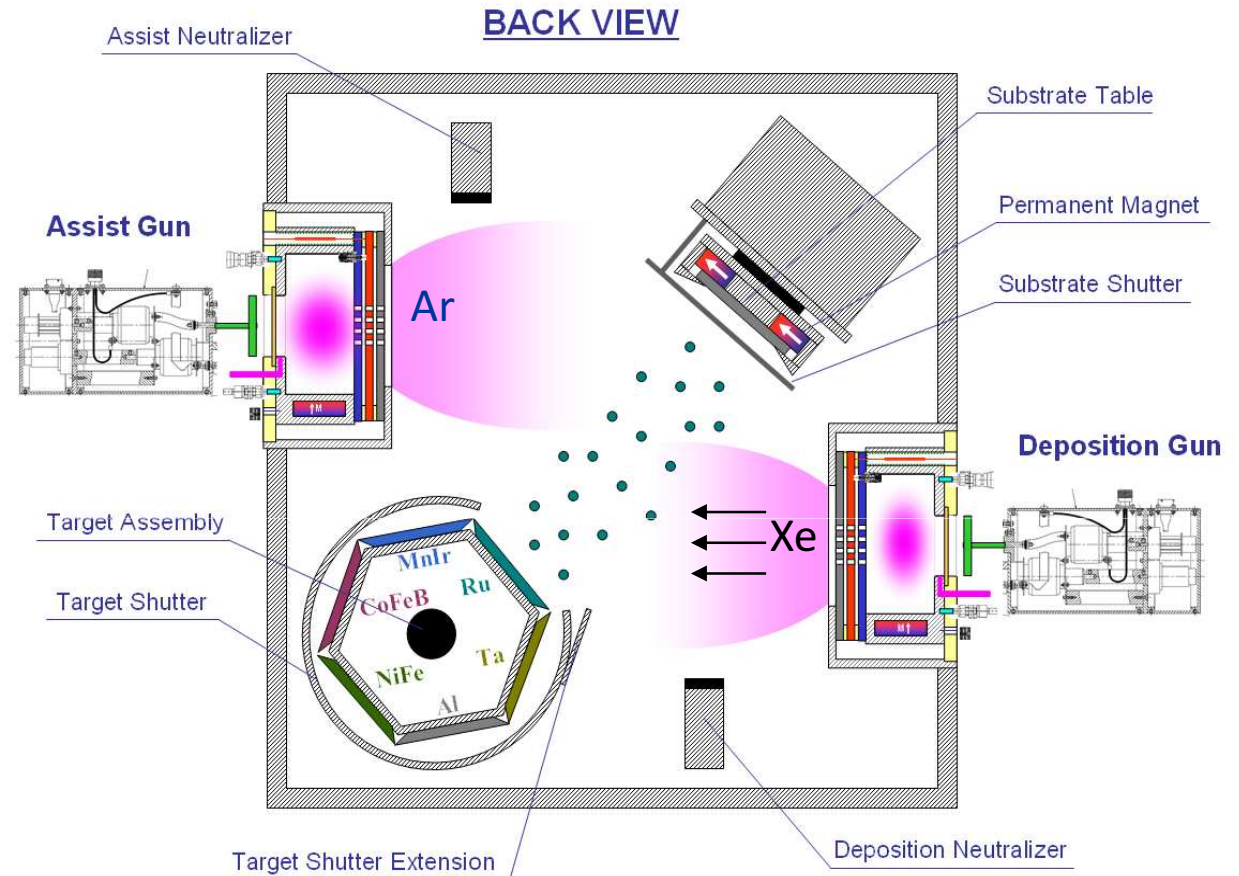
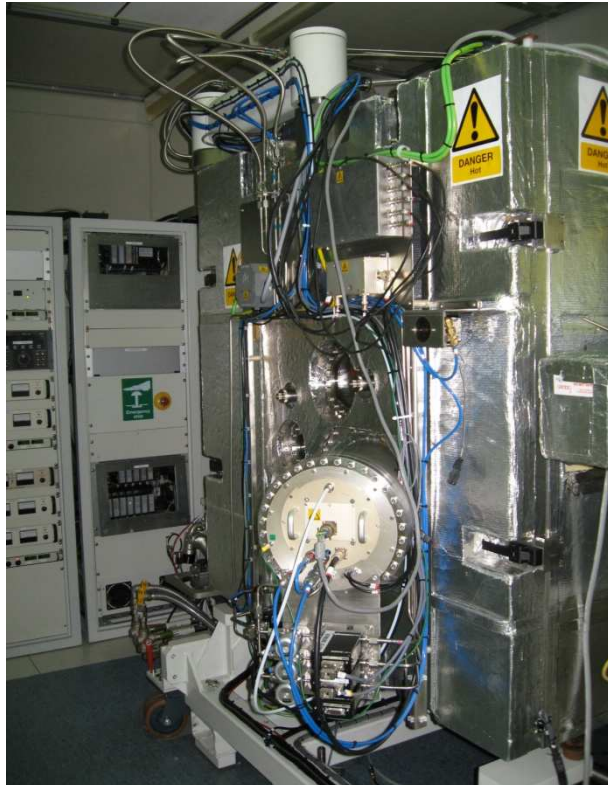


Ion Beam deposited MgO is always amorphous in the as-deposited state!



# Ion Beam Assisted Deposition

Nordiko 3600 Ion Beam Deposition Tool



## Ion Beam Assisted Deposition of MgO :

- An assistance Ar ion beam, directed to the substrate is used to provide extra energy to the atoms as they are deposited
- This extra energy can promote the crystallization of the MgO

# Ion Beam Assisted Deposition

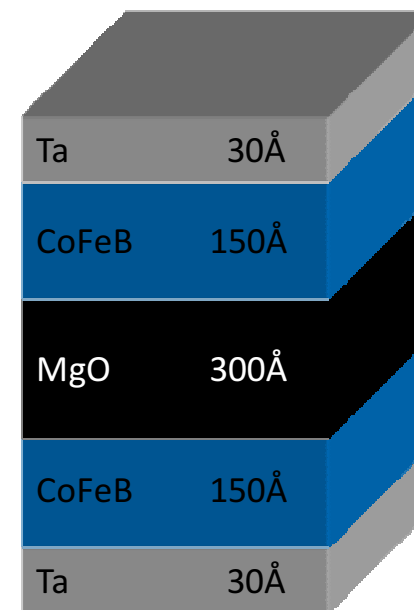
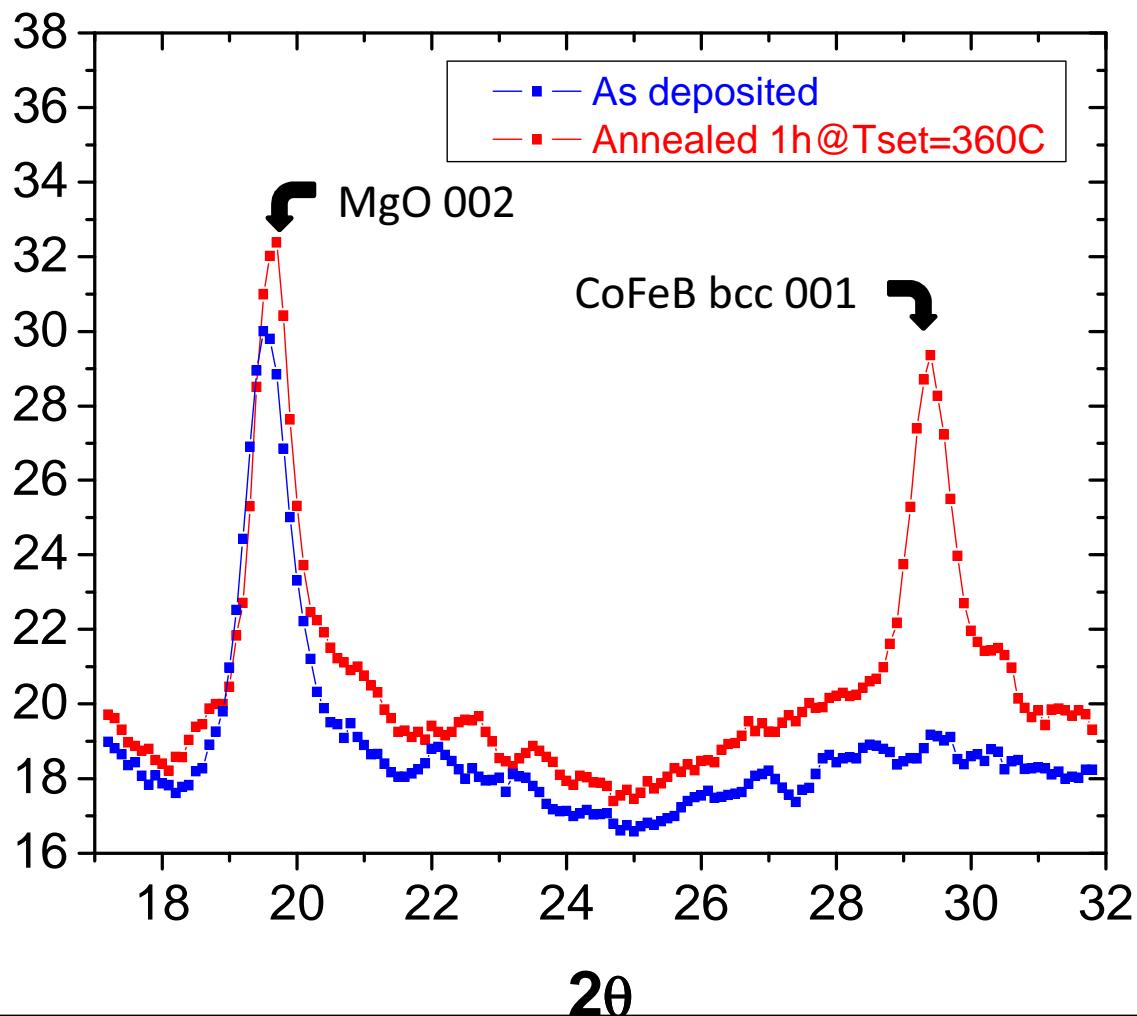
XRD diffraction of CoFeB/MgO/CoFeB stacks



## MgO Deposition Conditions:

Deposition Gun +138mA; +1000V/-275V | Assist Gun +95mA; +350V/-300V

X-ray Diffraction Intensity [cps]





# Ion Beam Assisted Deposition

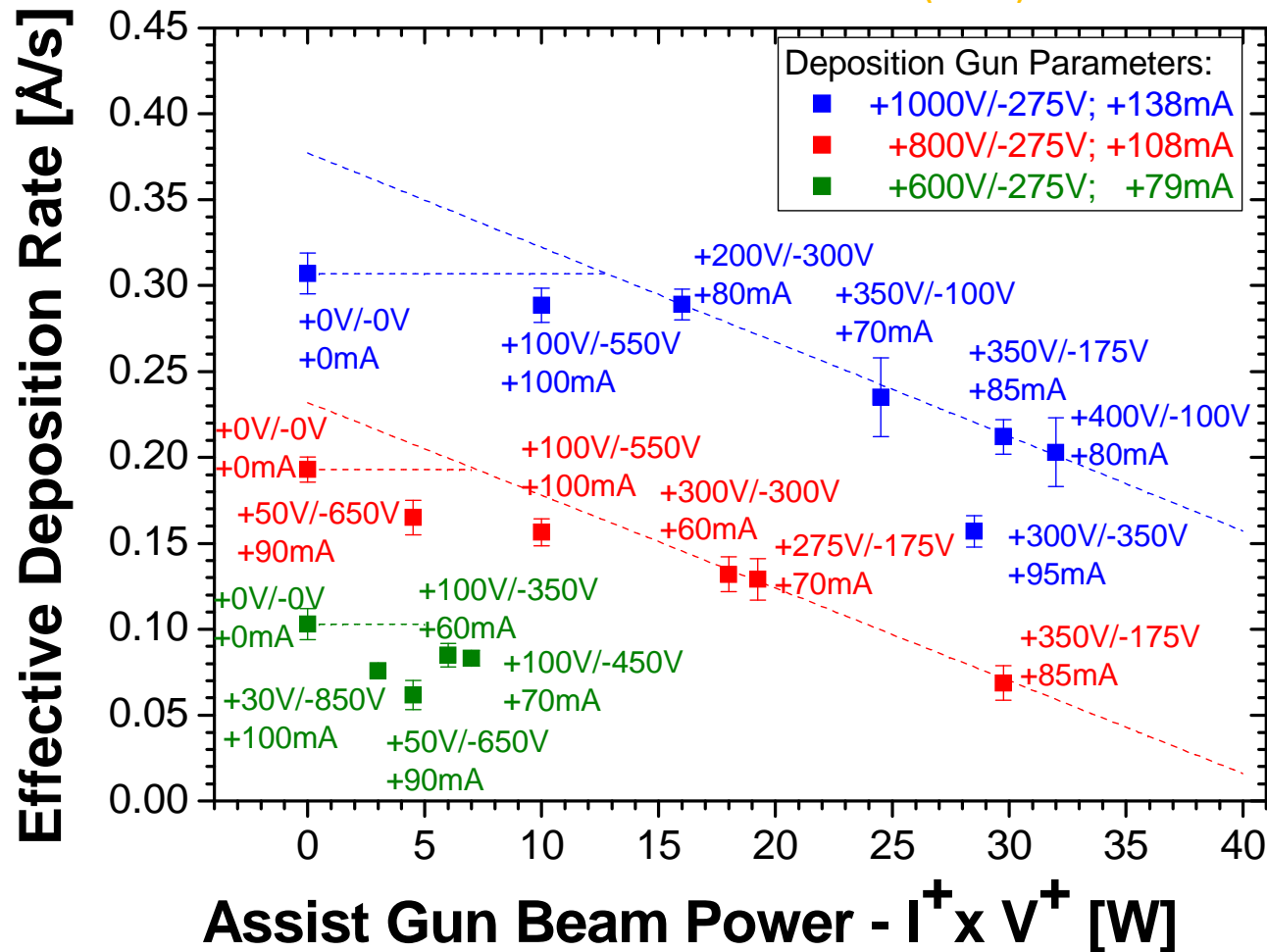
Deposition rate versus Assist Gun Beam Power



Effective Deposition Rate = Deposition Rate – Etch Rate

Deposition Rate  $\propto$  Dep Gun Beam Power ( $I^+ V^+$ )

Etch Rate  $\propto$  Assist Gun Beam Power ( $I^+ V^+$ )



# Ion Beam Assisted Deposition

Effect of Assist Gun Ion Energy ( $V^+$ )



Effective Deposition Rate = Deposition Rate – Etch Rate

Deposition Rate  $\propto$  Dep Gun Beam Power ( $I^+ V^+$ )

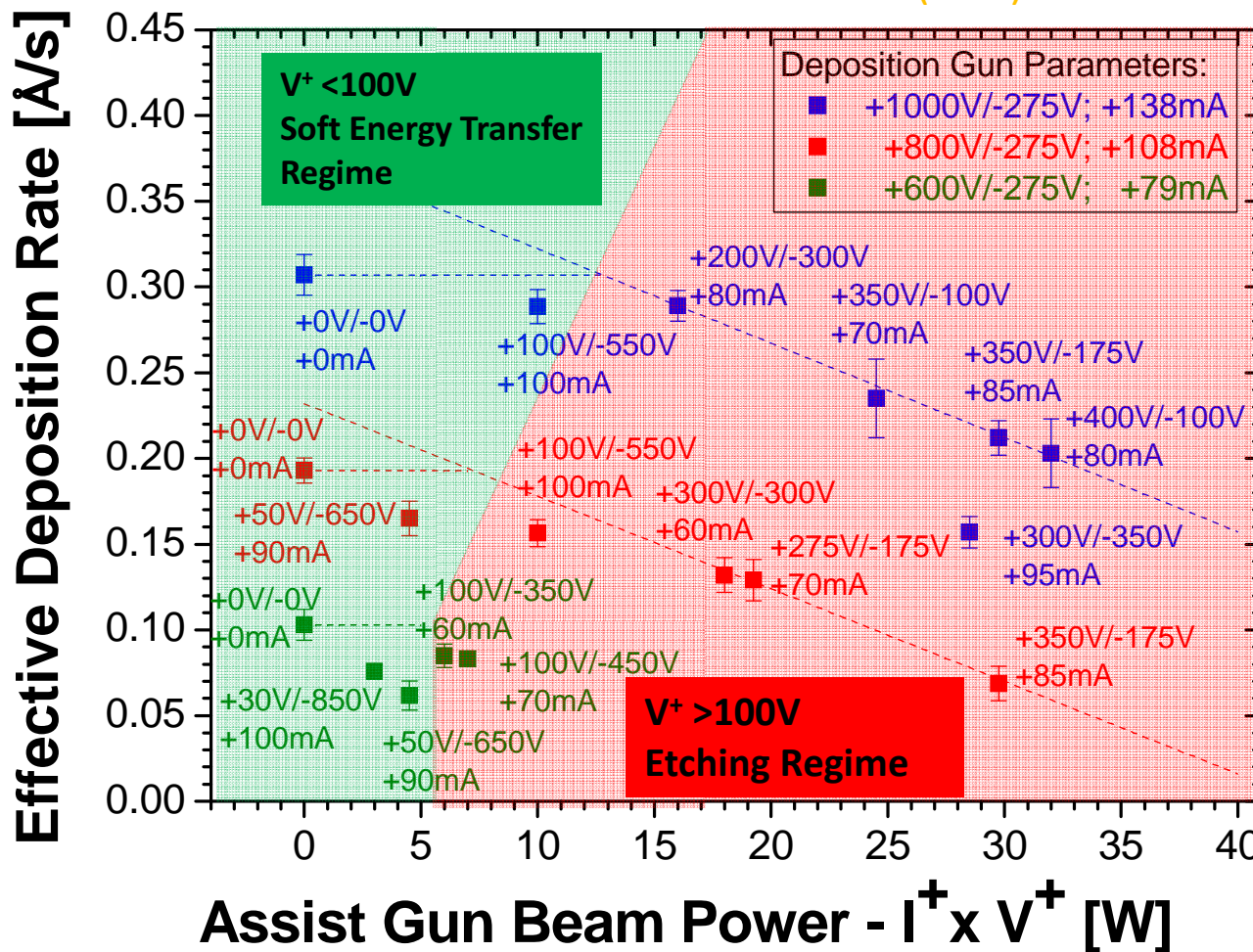
Etch Rate  $\propto$  Assist Gun Beam Power ( $I^+ V^+$ )

Assist  $V^+ < 100V$

Surface Effects



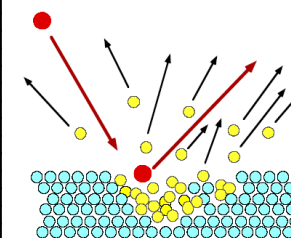
Assist beam ions enhance the mobility of surface atoms, without removing them.



Assist  $V^+ > 100V$

Bulk Effects

Etch Rate :  
0.0055  
 $\pm 0.0002$   
( $\text{\AA}/s$ ) / W



# Ion Beam Assisted Deposition

Effect of Assist Gun Beam Current ( $I^+$ )



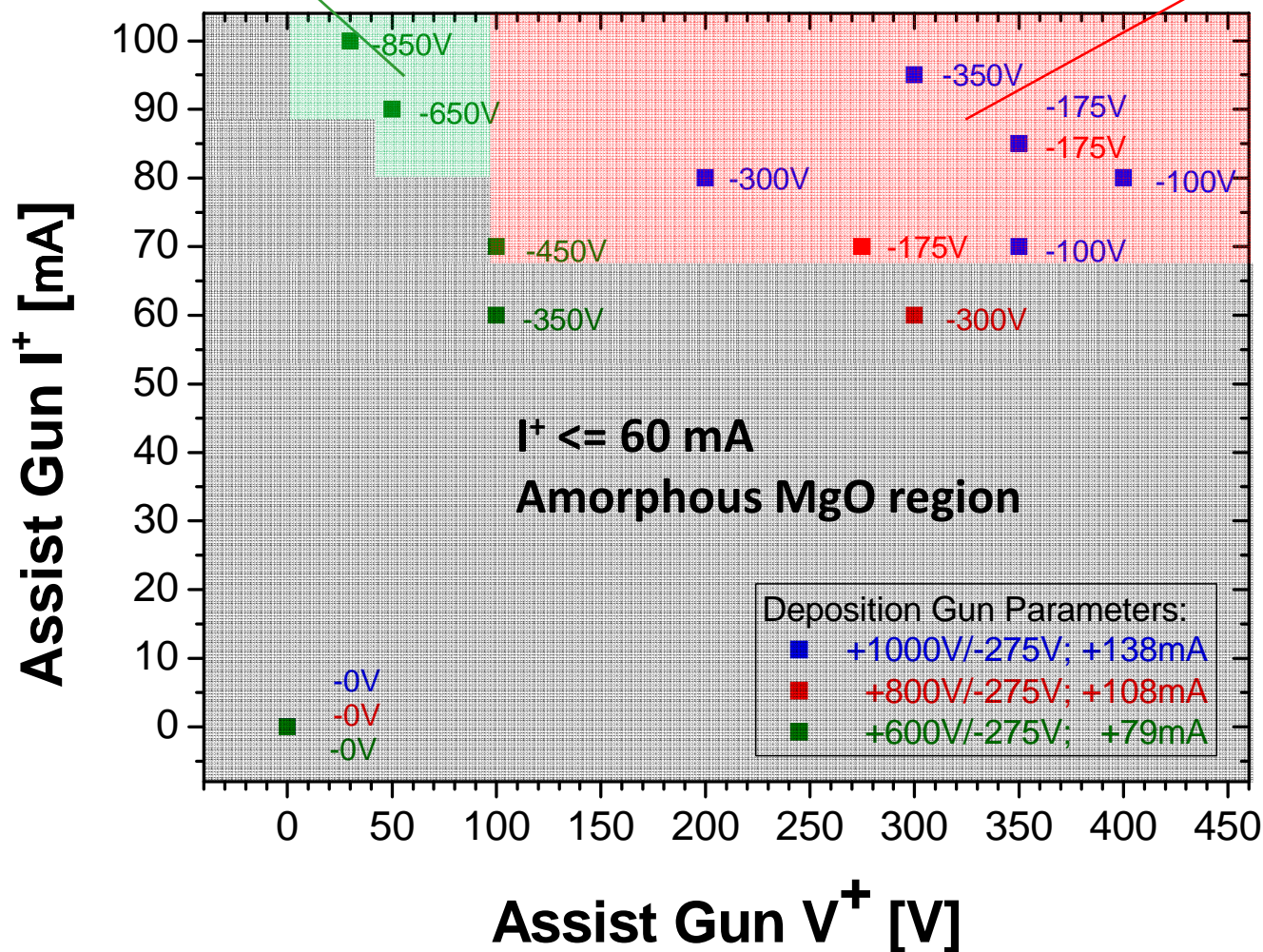
Soft Energy Transfer Regime

$I^+ \geq 80\text{mA}$  is required

Etch Regime

$I^+ \geq 70\text{mA}$

Crystalline MgO



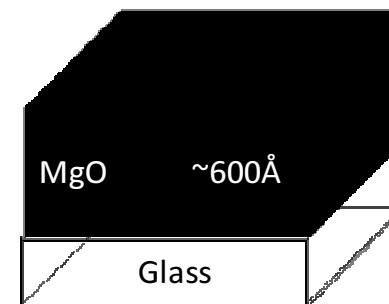
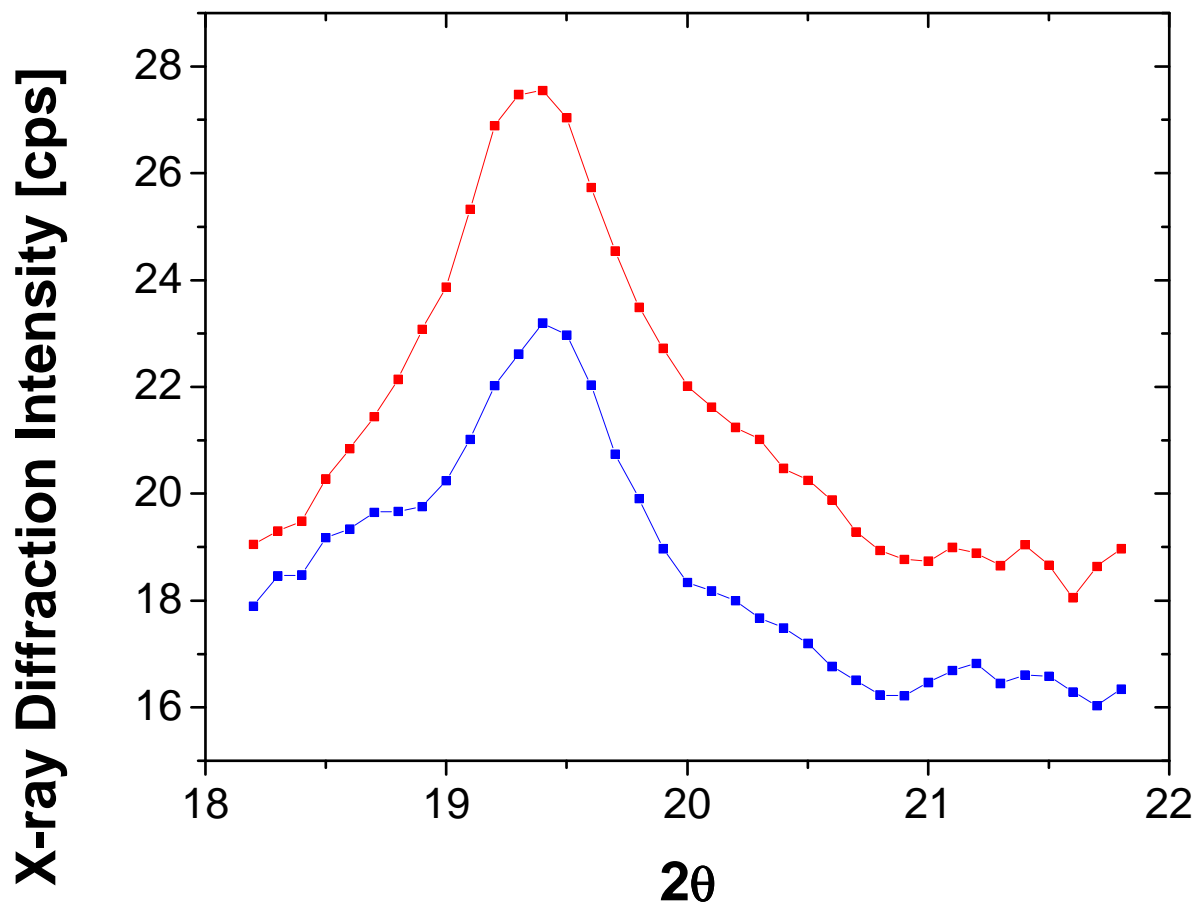
# Ion Beam Assisted Deposition

Effect of Assist Gun Beam Current ( $I^+$ )



MgO Deposition Conditions

- Dep Gun (+138mA; +1000V/-275V) | Assist Gun (+100mA; +100V/-550V)
- Dep Gun (+108mA; +800V/-275V) | Assist Gun (+100mA; +100V/-550V)



MgO texture is stronger for conditions with larger Ion/Atom ratio (Assist Gun  $I^+$  / Dep Gun  $I^+$ ).

The assist gun current required to promote MgO crystallization increases with decreasing assist gun voltage .

Soft Energy Transfer Regime is hard to get : very large currents are required for very low voltages in order to crystallize MgO

# X-ray Diffraction

Etching Regime versus Soft Regime : impact on MgO structure

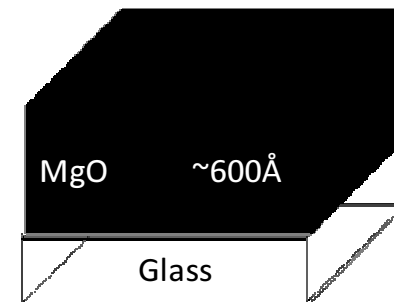
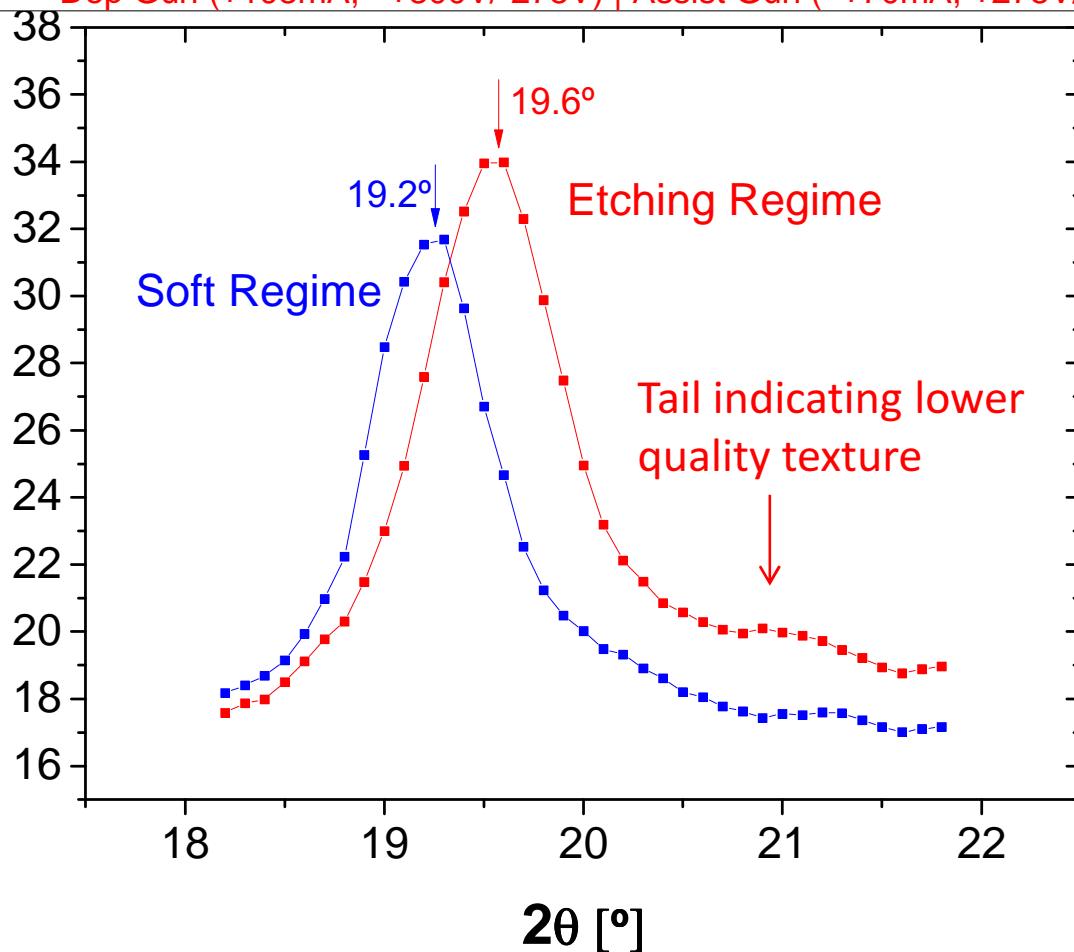


MgO Deposition Conditions

—■— Dep Gun ( +74mA; +600V/-275V) | Assist Gun (+100mA; +30V/-850V)

—■— Dep Gun (+108mA; +800V/-275V) | Assist Gun ( +70mA; +275V/-175V)

X-ray Diffraction Intensity [cps]



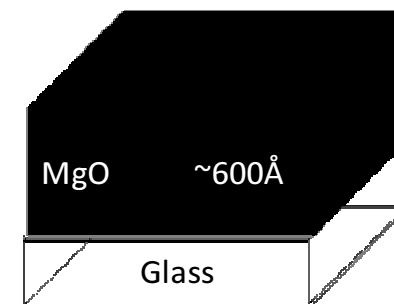
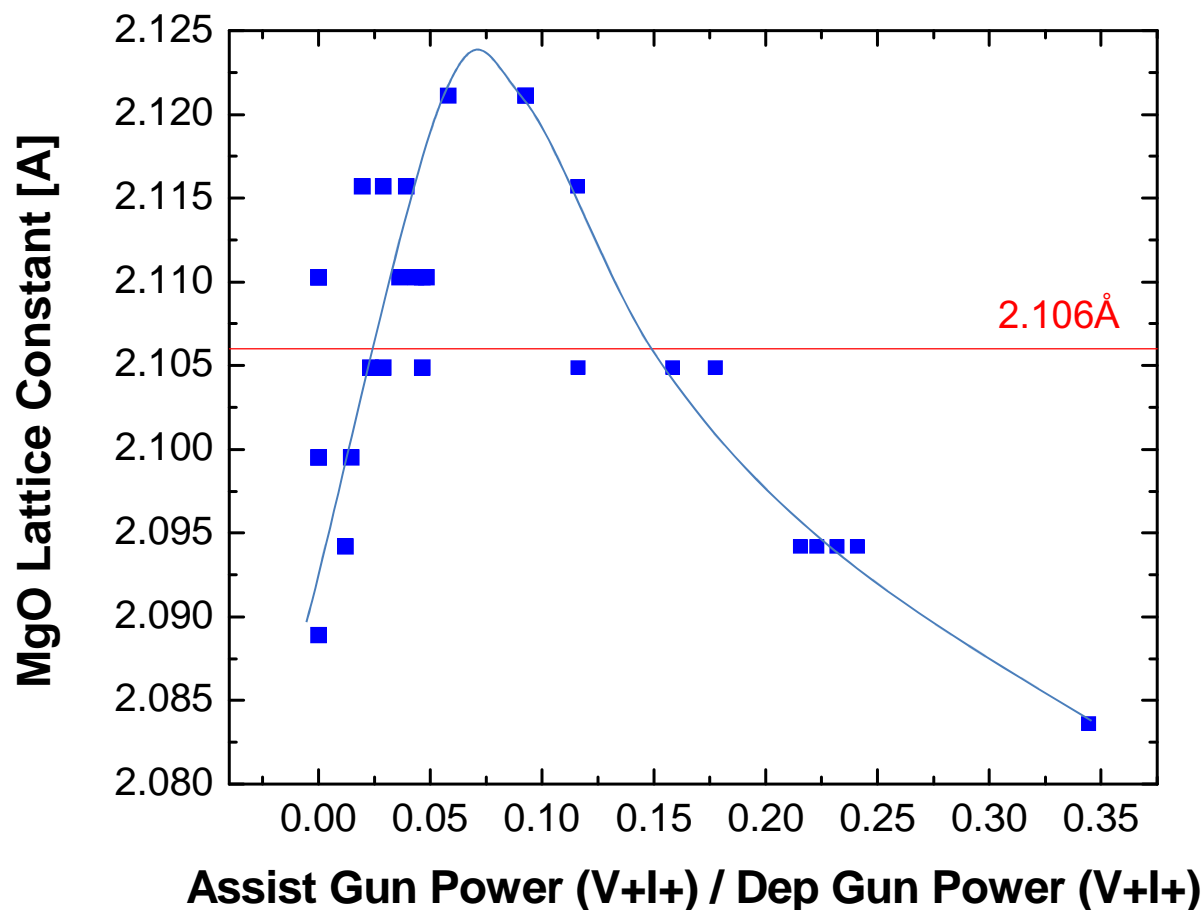
XRD Diffraction shows that:

- 1) Textured MgO can be obtained in both regimes
- 2) There are structural differences between the MgO deposited in the two regimes considered



# X-ray Diffraction

## MgO lattice constant tuning



MgO lattice constant can be changed by setting the ration between the assist gun power and the deposition gun power.

This feature can be used to reduce the mismatch between the MgO and CoFeB lattices.

# X-ray Diffraction

Etching Regime versus Soft Regime : structural differences

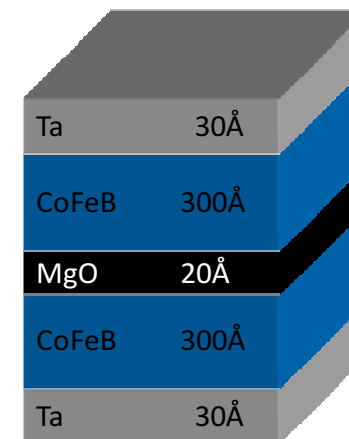
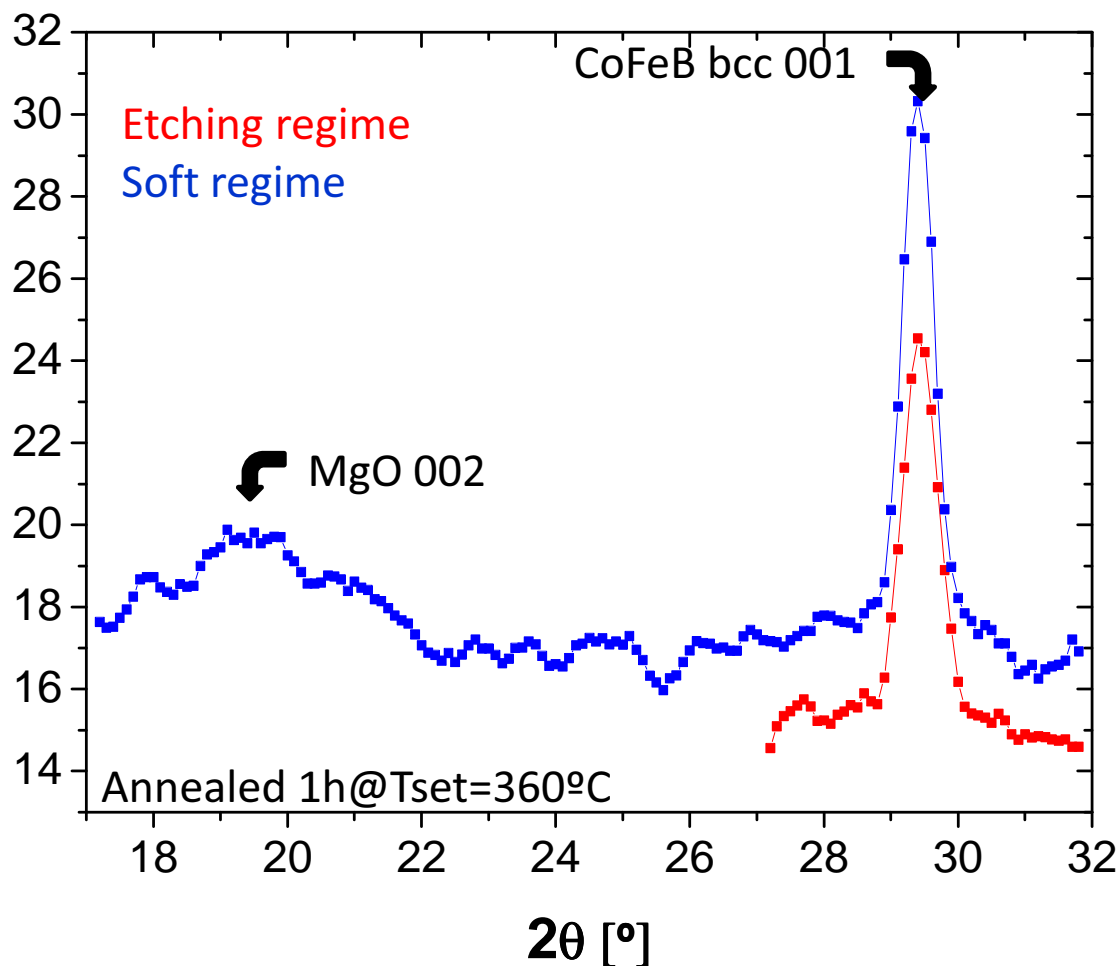


MgO Deposition Conditions

—■— Dep Gun ( +74mA; +600V/-275V) | Assist Gun (+100mA; +30V/-850V)

—■— Dep Gun (+108mA; +800V/-275V) | Assist Gun ( +70mA; +275V/-175V)

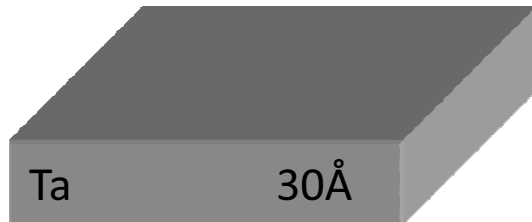
X-ray Diffraction Intensity [cps]



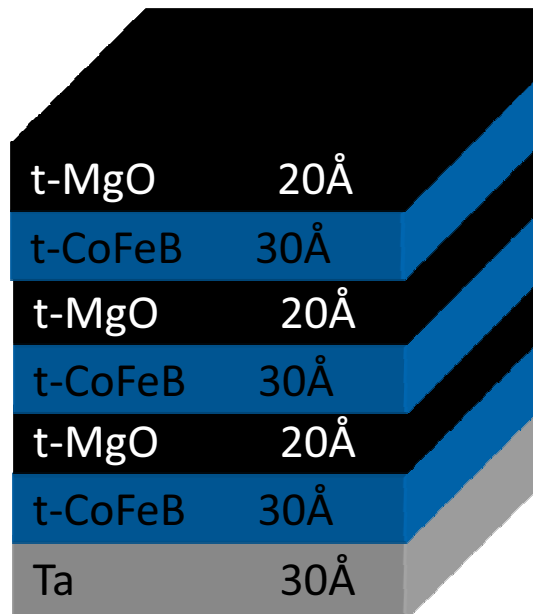
MgO deposited in the soft energy transfer regime is more efficient in promoting the texture of CoFeB upon annealing.

# HRTEM

Stacks prepared thin MgO and thin CoFeB layers



10 bi-layers



## MgO deposition conditions :

### 1) Soft Energy Transfer Regime

Deposition Gun : +600V; +74mA; 4.0 sccm Xe

Assist Gun : +30V/-850V; +100mA; 10sccmAr

### 2) Concurrent Etching Regime

Deposition Gun : +800V; +108mA; 4.0 sccm Xe

Assist Gun : +275V/-175V; +70mA; 10sccmAr

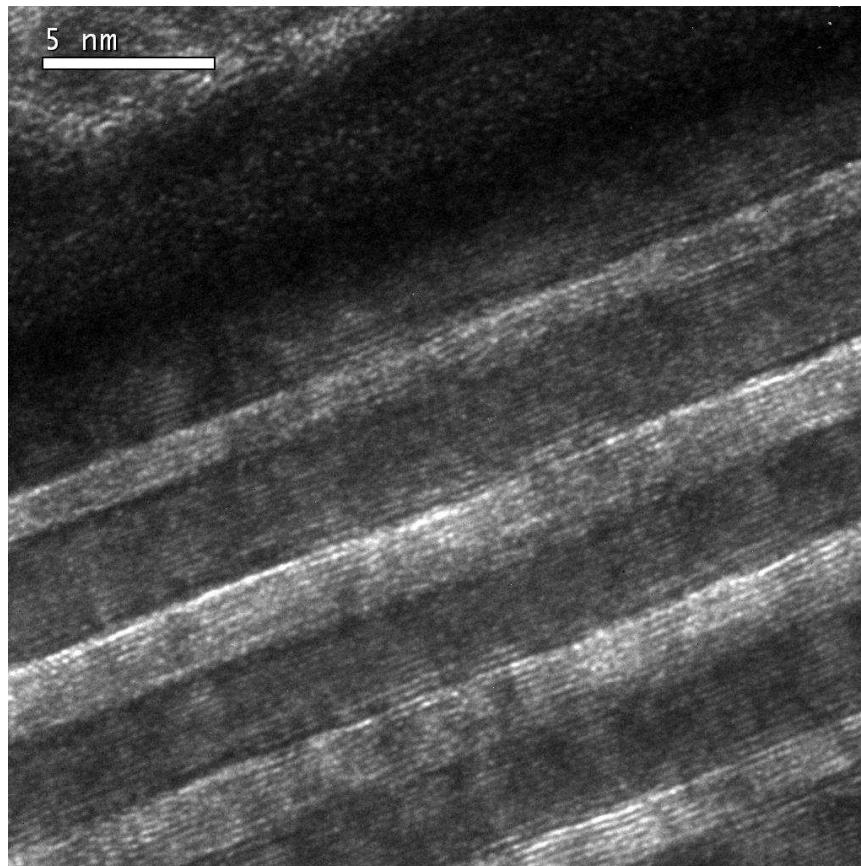
## CoFeB and Ta deposition conditions :

Deposition Gun : +1200V/-275V; +170mA; 4.0 sccm Xe

### Soft Energy Transfer Regime

Deposition Gun : +600V; +74mA; 4.0 sccm Xe

Assist Gun : +30V/-850V; +100mA; 10sccmAr

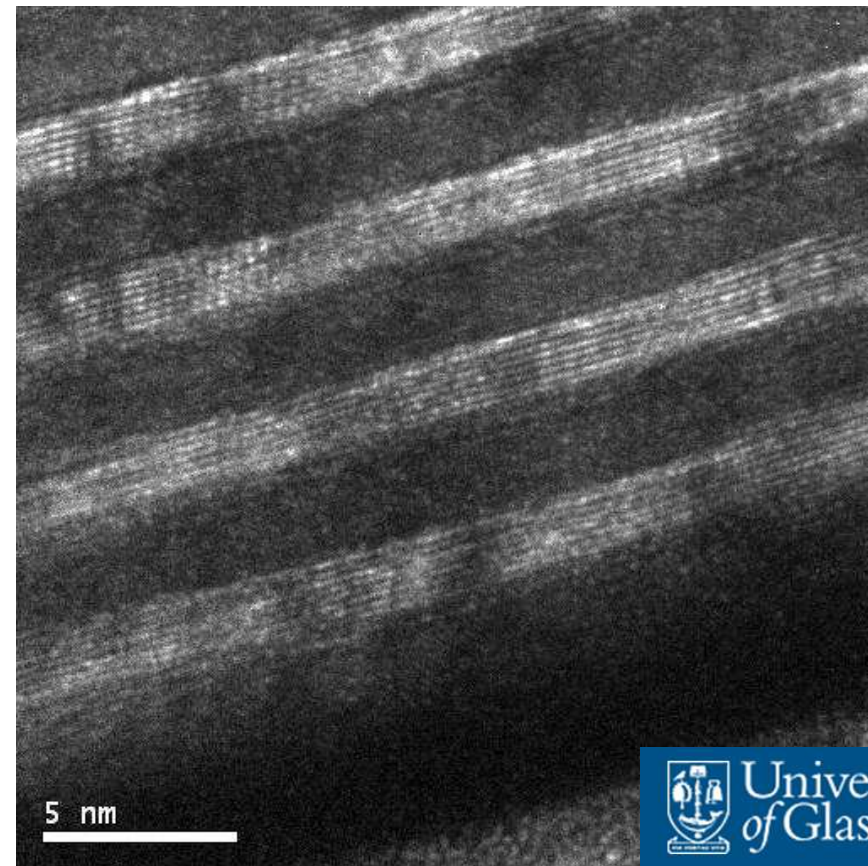


Mostly crystalline CoFeB

### Concurrent Etching Regime

Deposition Gun : +800V; +108mA; 4.0 sccm Xe

Assist Gun : +275V/-175V; +70mA; 10sccmAr



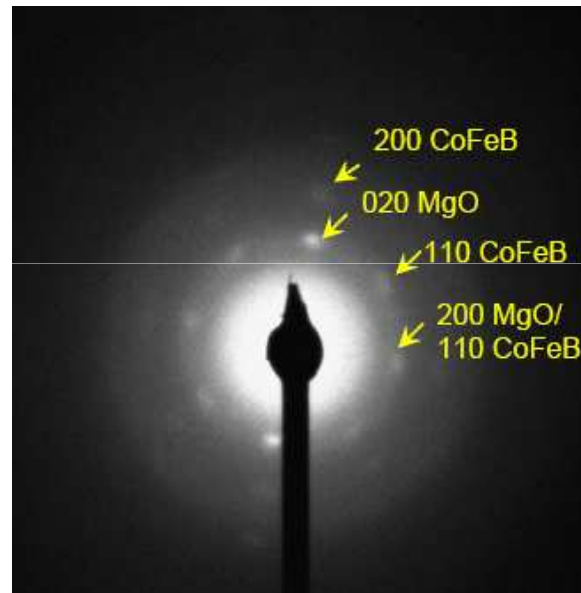
Mostly amorphous CoFeB



### Soft Energy Transfer Regime

Deposition Gun : +600V; +74mA; 4.0 sccm Xe

Assist Gun : +30V/-850V; +100mA; 10sccmAr

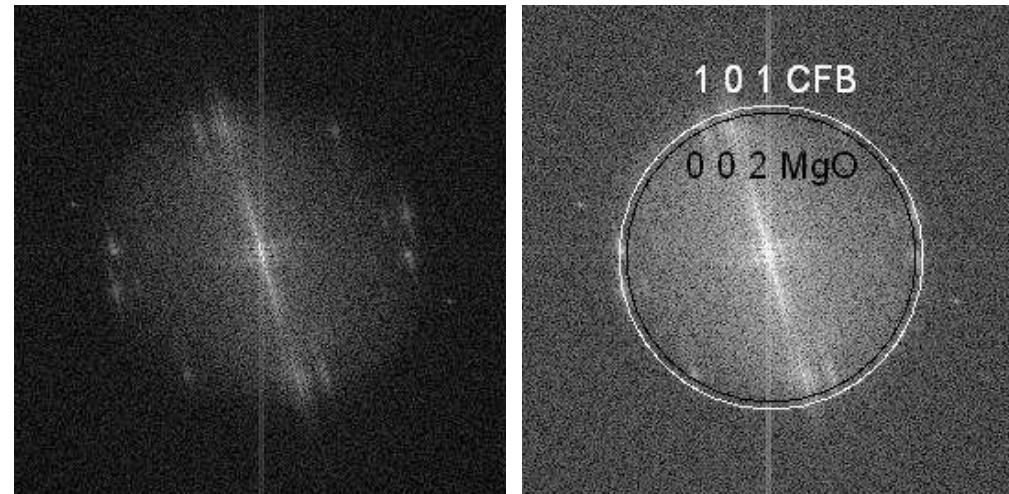


Selected Area Diffraction Pattern (SAD) shows strong out of plane [001] texture in all CoFeB and MgO layers

### Concurrent Etching Regime

Deposition Gun :+800V; +108mA; 4.0 sccm Xe

Assist Gun :+275V/-175V; +70mA; 10sccmAr



- Indexed reflections in the FFT suggest [001] texture of the MgO and mixed orientations for the CoFeB
- CoFeB does not exhibit crystalline properties everywhere



- Ion Beam Assisted Deposition is an effective technique to obtain strong textured CoFeB/MgO
- There are two assisted deposition regimes : soft energy transfer and concurrent etching regime
- XRD data and TEM show that the crystallization of CoFeB depends strongly on the assisted deposition conditions of MgO
- Data suggests that the best conditions to obtain high textured CoFeB/MgO are obtained with high current and low voltage assistance beams

The impact of the assisted deposition conditions on the transport properties of magnetic tunnel junctions is currently being determined





**Thank you for your attention!**

**Questions?**